EPO-TEK® T6065

Technical Data Sheet
For Reference Only
Thermally Conductive Epoxy

Date:	May 2026
Rev:	IV
No. of Components:	Single
Mix Ratio by Weight:	N/A
Specific Gravity:	1.68
Pot Life:	28 Days
Shelf Life- Bulk:	One year at -40°C
Shelf Life- Syringe:	One year at -40°C

Recommended Cure: 180°C / 1 Hour

NOTES:
- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® T6065 is a single component, high Tg, thermally conductive, semiconductor die-attach grade epoxy. It was designed for bonding chips and SMD's inside hybrid micro-electronic packages. Other applications include JEDEC and opto-electronic packaging.

Typical Properties: Cure condition: 180°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:				
* Color (before cure):	White			
* Consistency:	Smooth paste			
* Viscosity (23°C) @ 2.5 rpm:	80,000-120,000		cPs	
Thixotropic Index:	1.9			
* Glass Transition Temp:	≥ 100		°C (Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):				
Below Tg:	38		x 10^{-6} in/in°C	
Above Tg:	136		x 10^{-6} in/in°C	
Shore D Hardness:	92			
Lap Shear @ 23°C:	> 2,000		psi	
Die Shear @ 23°C:	≥ 20		Kg 7,112 psi	
Degradation Temp:	397		°C	
Weight Loss:				
@ 200°C:	0.10		%	
@ 250°C:	0.16		%	
@ 300°C:	0.30		%	
Suggested Operating Temperature:	< 300		°C (Intermittent)	
Storage Modulus:	816,394		psi	
Ion Content:	Cl^-:	135 ppm	Na^+:	48 ppm
	NH_4^+:	105 ppm	K^+:	6 ppm
* Particle Size:	≤ 20		microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	0.8	W/mK
Volume Resistivity @ 23°C:	≥ 1.2 x 10^{14}	Ohm-cm
Dielectric Constant (1KHz):	5.30	
Dissipation Factor (1KHz):	0.011	

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EPO-TEK® T6065 Advantages & Suggested Application Notes:

- Viscosity is suitable for automatic syringe dispensers, although it can be applied by screen printing or manual hand operations.
- Performs exceptionally well as a die-attach for small chips such as GaAs, LEDs, diodes and SMD components.
- Capable of resisting 260°C green reflow process, low outgassing hermetic lid-seal processes near 300°C, and organic burn-in up to 150° C/1000 hours storage.
- Capable of JEDEC Level II die attach packaging on die paddles and lead frames.
- Widely used epoxy; popular choice for non-silver-fille die-attach epoxies; opto-packaging; hybrids, and many types of substrates including kovar, ceramic, and BT.
- Available in many different viscosity ranges – contact Technical Services at techserv@epotek.com for best recommendation.
- Can be used as a non-conductive stacking epoxy, in conjunction with EPO-TEK® E3035, for attaching SMDs to the hybrid circuit

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